

L Number	Hits	Search Text	DB	Time stamp
	6	(dicing adj tape) same (transfer tape) same (etched adj ports)	USPAT; US-PPGPUB; EPO; JPO; DERWENT USPAT;	2004/04/26 15:03
	6	(dicing adj tape) with (through adj hole) with backside	US-PPGPUB; EPO; JPO; DERWENT USPAT	2003/11/12 18:10
	13	("4791075"   "4907065"   "5150196"   "5323051"   "5362681"   "5435876"   "5610431"   "5824177"   "5831162"   "6106735"   "6109113"   "6210514"   "6410360").PN.	DERWENT USPAT	2003/11/12 18:09
	6	(dicing adj tape) same (through adj hole) same backside	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/12 18:11
	12	((dicing adj tape) and ((hole or via or open\$3 or interconnect) with (substrate or wafer)) and (transfer adj tape))	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/12 18:39
	194	((dicing adj tape) and ((hole or via or open\$3 or interconnect) with (substrate or wafer))	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/12 18:40
	53	(dicing adj tape) same ((hole or via or open\$3 or interconnect) with (substrate or wafer))	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/12 18:42
	20	((dicing adj tape) same ((hole or via or open\$3 or interconnect) with (substrate or wafer))) and @ad<20001205	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/12 19:00
	26	(dicing adj tape) with wafer with backside	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/12 18:58
	148	tape with wafer with backside	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/12 18:59
	246	tape with (wafer or substrate) with backside	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/12 18:59
	1713	(hole or open\$3 or via or interconnect) with (wafer or substrate) with backside	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/12 19:00
	38	(tape with (wafer or substrate) with backside) and ((hole or open\$3 or via or interconnect) with (wafer or substrate) with backside)	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/12 19:00
	22	((tape with (wafer or substrate) with backside) and ((hole or open\$3 or via or interconnect) with (wafer or substrate) with backside)) and dic\$3	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/12 19:00
	6	((tape with (wafer or substrate) with backside) and ((hole or open\$3 or via or interconnect) with (wafer or substrate) with backside)) and dic\$3) and @ad<20001205	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/12 19:00
	2	5362681.pn.	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/11/13 11:56
	56	5362681.URPN.	USPAT	2003/11/13 11:53

	6315	((bottom or (back adj side)) with (tape or adhesive) same (dic\$3 or cut\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 11:57
	469	((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate) same (dic\$3 or cut\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 11:58
	257327	(wafer or substrate) with (via hole open\$3 interconnect)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 11:59
	80	((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate) same (dic\$3 or cut\$4)) same ((wafer or substrate) with (via hole open\$3 interconnect))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 14:27
	0	((((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate) same (dic\$3 or cut\$4)) same ((wafer or substrate) with (via hole open\$3 interconnect))) and 5362681.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 11:59
	8	5362681.URPN. and (((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate) same (dic\$3 or cut\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 16:29
	1	007585.apn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 12:12
	43	((((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate) same (dic\$3 or cut\$4)) same ((wafer or substrate) with (via hole open\$3 interconnect))) and @ad<20001205 ("4872825"   "4933744"   "5178957"   "5497033"   "5685885"   "5730922"   "5747101"   "5761801"   "5766979"   "5848467"   "5866952"   "5958995"   "5962608"   "5971253"   "6007407").PN.	USPAT	2003/11/13 12:12
	15		USPAT	2003/11/13 12:35
	344	((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate) same (dic\$3 or cut\$4)) and ((wafer or substrate) with (bottom or (back adj side) with etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 14:29
	323	((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate) same (dic\$3 or cut\$4)) same ((wafer or substrate) with (bottom or (back adj side) with etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 14:29
	64	((((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate) same (dic\$3 or cut\$4)) same ((wafer or substrate) with (bottom or (back adj side) with etch\$3))) and 438/\$3.cc1s.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:20
	28	(((((bottom or (back adj side)) with (tape or adhesive) with (wafer or substrate) same (dic\$3 or cut\$4)) same ((wafer or substrate) with (bottom or (back adj side) with etch\$3))) and 438/\$3.cc1s.) and @ad<20001205	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:31
	8	uv with tape with needle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 16:31
	11	(uv with tape) same needle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 16:33

	10	(ultraviolet with tape) same needle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 16:39
	72	(ultraviolet with adhesive) same needle	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 16:40
	6	((ultraviolet with adhesive) same needle) same dic\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:03
	7	(transfer adj tape) with (dicing adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 19:04
	1389	(transfer adj tape) with (adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:30
	6	((transfer adj tape) with (adhesive)) with dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:05
	6	((transfer adj tape) with (adhesive)) same dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:05
	11	(transfer adj tape) with dicing	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:06
	7	(transfer adj tape) same (dicing adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:28
	15	((transfer adj tape) with (adhésivé)) and 438/\$3.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:30
	0	(pickup adj tape) same (dicing adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:28
	2	(pickup adj tape) and (dicing adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:28
	236	(dicing adj tape) with (adhesive)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:30
	70	((dicing adj tape) with (adhesive)) and 438/\$3.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:31
	24	((dicing adj tape) with (adhesive)) and 438/\$3.cccls.) and @ad<20001205	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 17:31
	6	(releas\$3 adj tape) with (dicing adj tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/13 19:05
	1	006966.apn,	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/11/14 11:34
	0	((dic\$3 adj tape) same (mem or mems)) and (@ad<20001205 or @rlad<20001205)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/26 15:24

	11	(dic\$3 adj tape) same (mem or mems)	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2004/04/26 15:24
	13	("4791075"   "4907065"   "5150196"   "5323051"   "5362681"   "5435876"   "5610431"   "5824177"   "5831162"   "6106735"   "6109113"   "6210514"   "6410360") :PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2004/04/26 15:15
	26	(dic\$3 adj tape) and (mem or mems)	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2004/04/26 15:24
	11	((dic\$3 adj tape) and (mem or mems)) and (@ad<20001205 or @rlad<20001205)	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2004/04/26 16:37
	132	438/45\$1.ccls. and (mems or mem)	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2004/04/26 16:37
	75	(438/45\$1.ccls. and (mems or mem)) and (@ad<20001205 or @rlad<20001205)	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2004/04/26 16:37
	1	((438/45\$1.ccls. and (mems or mem)) and (@ad<20001205 or @rlad<20001205)) and (dic\$3 with tape)	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2004/04/26 16:50
	4	((438/45\$1.ccls. and (mems or mem)) and (@ad<20001205 or @rlad<20001205)) and tape	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2004/04/26 16:50
	8	("5187007"   "5476566"   "5605489"   "5923995"   "6010782"   "6245593"   "6297131"   "6320266") :PN.	USPAT	2004/04/26 17:05